2SB0774 (2SB774)

Silicon PNP epitaxial planar type

For low-frequency amplification

Features

- \bullet High emitter-base voltage (Collector open) V_{EBO}
- Protective diodes and resistances between emitter and base can be omitted.

Unit: mm

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-30	v	
Collector-emitter voltage (Base open)	V _{CEO}	-25	V	
Emitter-base voltage (Collector open)	V _{EBO}	-15	V	
Collector current	I _C	-100	mA	
Peak collector current	I _{CP}	-200	mA	
Collector power dissipation	P _C	400	mW	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°Ç	

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, I_{\rm E} = 0$	-30	S		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-25	0		V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \ \mu A, I_{\rm C} = 0$	-15			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -10 \text{ V}, I_E = 0$			-1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -20 \text{ V}, I_B = 0$			-100	μΑ
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -10 \text{ V}, I_C = -2 \text{ mA}$	210		460	
	h _{FE2}	$V_{CE} = -2 V, I_C = -100 mA$	90			_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -100 \text{ mA}, I_{\rm B} = -10 \text{ mA}$			- 0.5	V
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance (Common-emitter reverse transfer)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		4		pF

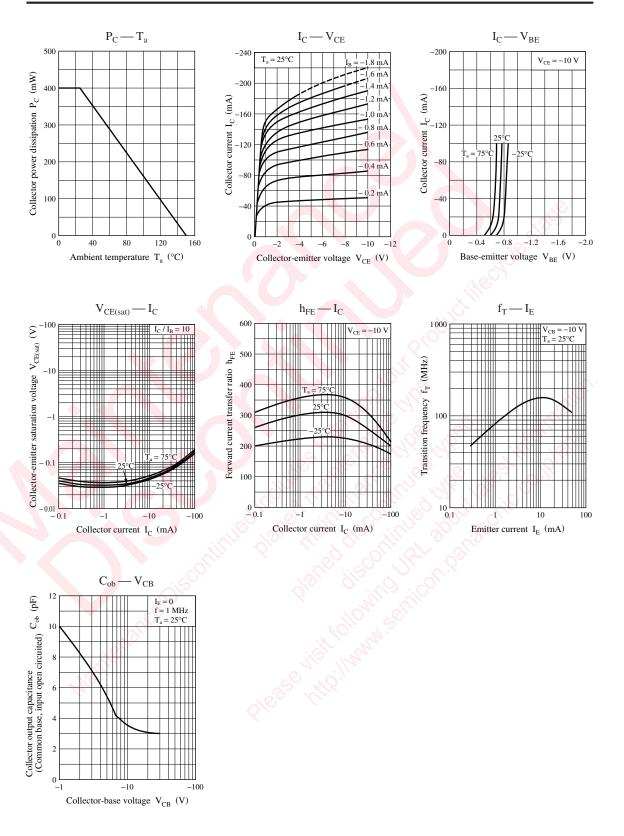
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	S
h _{FE1}	210 to 340	290 to 460

Note) The part number in the parenthesis shows conventional part number.

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